

to prepare water-soluble photosensitive resin compositions (Comparative Examples 1 to 13 and Examples 1-4).

[Please amend paragraph [0057] as follows:]

[0057] (ii) Production of photosensitive resin plates of Comparative Examples 1 to 13 and Examples 1 to 4:

Each of the above-described water-soluble photosensitive resin compositions of Comparative Examples 1 to 13 and Examples 1 to 4 was coated onto a polyester film (cover film), followed by drying to form a photosensitive layer of 0.7 mm in thickness. Then, a base was adhered thereto to provide photosensitive resin plates (raw plates or to-be-exposed plates) of Comparative Examples 1 to 13 and Examples 1 to 4.

[Please amend paragraph [0058] as follows:]

[0058] (iii) Evaluation of Depth of Non-printing area:

After each of the cover film was released from the photosensitive resin plates of Comparative Examples 1 to 13 and Examples 1 to 4, the photosensitive resin plates of Comparative Examples 1 to 13 and Examples 1 to 4 were exposed through a mask having independent fine lines of 150 μm , using a chemical lamp of 20 W from a distance of 45 mm for 10 minutes, and then, the unexposed areas were removed by washing out with water of 35°C using a brush, followed by drying at 80°C for 5 minutes to make printing plates.

Please amend paragraph [0060] as follows:

[0060] Comparative Examples 14 to 26 and Examples 5 to 8

By following the same procedures as Comparative Examples 1- 13 and Examples 1 to 4 above, except that o-toluenesulfonamide was used instead of p-toluenesulfonamide, water-soluble photosensitive resin compositions of Comparative Examples 14 to 26 and Examples 5 to 8 were prepared, and photosensitive resin plates of Comparative Examples 14 to 26 and Examples 5 to 8 were obtained.

[Please amend paragraph [0061] as follows:]

CZ
AZ [0061] Using the plates of Comparative Examples 14 to 26 and Examples 5 to 8, the depth was evaluated in the same manner as described in Comparative Examples 1 - 13 and Examples 1 to 4 above. The results are shown in Table I.

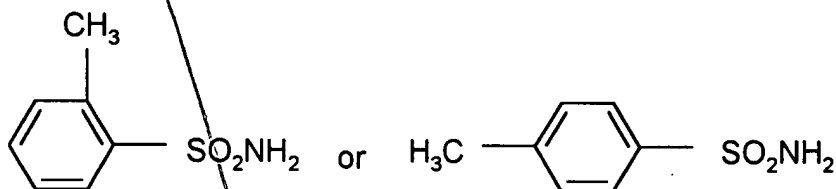
Please replace Table I on page 23 of the specification with Table I submitted herewith on a separate sheet.

IN THE CLAIMS:

Please amend claim 1 as follows:

1. (Amended) A negative-working photosensitive composition comprising:
- (A) a film-forming polymer
 - (B) an unsaturated compound having a radical polymerizable ethylenic double bond,
 - (C) a photopolymerization initiator,
 - (D) a thermal polymerization inhibitor, and
 - (E) at least one member selected from compounds represented by the following

Q4
Sub B1
formula:



in an amount of 1.0 - 2.0 wt% based on the weight of the photosensitive resin composition.

Please cancel claim 2 without prejudice to the subject matter thereof.